#### SCOPE:

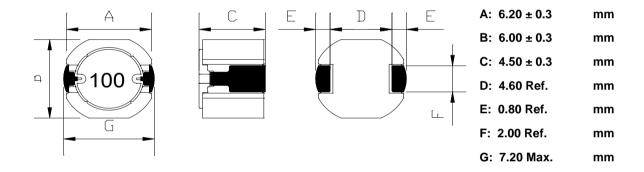
This specification applies to the Pb Free high current type SMD inductors for MSCDRI-6045TH0-SERIES

#### PRODUCT INDENTIFICATION

MSCDRI - 6045T H0 - 100 M

- (1)
- ②
- 3 4 5
- **1** Product Code
- **② Dimensions Code**
- 3 AEC-Q200 Code
- **4** Inductance Code
- **⑤ Tolerance Code**

## (1) SHAPES AND DIMENSIONS



# (2) ELECTRICAL SPECIFICATIONS SEE TABLE 1

TEST INSTRUMENTS

L: HP 4284A PRECISION LCR METER (or equivalent)

RDC: CHROMA MODEL 16502 MILLIOHMMETER (or equivalent)

## (3) CHARACTERISTICS

(3)-1 Operate temperature range .....  $-40^{\circ}$ C  $\sim +155^{\circ}$ C (Including self temp. rise)



#### **TABLE 1**

MAGLAYERS	Inductance	Percent	Test	Resistance	Rated Do	C Current	Marking
PT/NO.	L(µH)	Tolerance	Frequency	RDC(Ω)Max.	Isat(A)	Irms(A)	Warking
MSCDRI-6045TH0-100□	10	M,N	100kHz/0.25V	83.7m	2.10	2.10	100
MSCDRI-6045TH0-150	15	M,N	100kHz/0.25V	0.15	1.70	1.70	150
MSCDRI-6045TH0-220	22	M,N	100kHz/0.25V	0.19	1.40	1.40	220
MSCDRI-6045TH0-101□	100	M,N	100kHz/0.25V	0.68	0.61	0.61	101
MSCDRI-6045TH0-221□	220	M,N	100kHz/0.25V	1.60	0.47	0.47	221
MSCDRI-6045TH0-471	470	M,N	100kHz/0.25V	3.34	0.28	0.28	471

 $\mbox{\@model{\times}} \ \square$  specify the inductance tolerance M(±20%) , N(±30%)

※ Isat: Based on inductance change (△L/Lo: drop 30% Max.) @ambient Temperature: 25℃

Irms: Based on temperature rise ( $\triangle T$ : 40°C Typ.) Rated DC Current: The less value which is lsat or Irms.



# (4) RELIABILITY TEST METHOD ELECTRICAL

TEST ITEM	SPECIFICATION	TEST DETAILS
Insulation	There shall be	DC 100V voltage shall be applied across this sample of top
resistance	no other	surface and the terminal.
	damage or	The insulation resistance shall be more than $1 \times 10^8 \Omega$ .
	problems.	
Dielectric	There shall be	AC 100V voltage shall be applied for 1 minute acrosset the top
withstand	no other	surface and the terminal of this sample
voltage	damage or	
	problems.	
Temperature	∆L/L20°C≦±10%	The test shall be performed after the sample has stabilized in
characteristics	0~2000 ppm/℃	an ambient temperature of -20 to +85℃,and the value
		calculated based on the value applicable in a normal
		temperature and narmal humidity shall be △L/L20°C ≦±10%.

#### **MECHANICAL**

TEST ITEM	SPECIFICATION	TEST DETAILS	
Substrate bending	∆L/Lo≦±5%	The sample shall be soldered onto the printed circuit board	
	There shall be	in figure 1 and a load applied unitil the figure in the arrow	
	no mechanical	direction is made approximately 3mm.	
	damage or elec-	60 sec minimum holding time.	
	trical damage.	PCB dimension shall the page 7/9	
		F(Pressurization)	
		$\Box$	
		R5 45±2 45±2	
		10 20 R340	
		PRESSURE ROD figure-1	
Flammability	There shall be	Burning stops within 10 seconds on a vertical specimen; drips of	
	no other	particles allowed as long as they are not inflamed.	
	damage or		
	problems.		
Terminal Strength	There shall be	With the component mounted on a PCB obtained from the	
Terminal Strength	There shall be no other	With the component mounted on a PCB obtained from the Supplier with the device to be tested, apply a 17.7 N (1.8 Kg) force to the side of a device being tested. This force shall be applied for	
Terminal Strength		Supplier with the device to be tested, apply a 17.7 N (1.8 Kg) force	
Terminal Strength	no other	Supplier with the device to be tested, apply a 17.7 N (1.8 Kg) force to the side of a device being tested. This force shall be applied for	
Terminal Strength  Mechanical Shock	no other damage or	Supplier with the device to be tested, apply a 17.7 N (1.8 Kg) force to the side of a device being tested. This force shall be applied for	
-	no other damage or problems.	Supplier with the device to be tested, apply a 17.7 N (1.8 Kg) force to the side of a device being tested. This force shall be applied for 60 +1 seconds.	
-	no other damage or problems.  △L/Lo≤±5%	Supplier with the device to be tested, apply a 17.7 N (1.8 Kg) force to the side of a device being tested. This force shall be applied for 60 +1 seconds.	



#### **MECHANICAL**

TEST ITEM	SPECIFICATION		
Vibration	△L/Lo≦±5%  There shall be no mechanical damage.	5g's for 20 minutes, 12 cycles each of 3 orientations.  Test from 10-2000 Hz.	
Solderability	New solder More than 90%	Flux (rosin, isopropyl alcohol{JIS-K-1522}) shall be coated over the whole of the sample before hard, the sample shall then be preheated for about 2 minutes in a temperature of 130~150°C and after it has been immersed to a depth 0.5mm below for 3±1 seconds fully in molten solder M705 with a temperature of 245±5°C.  More than 90% of the electrode sections shall be couered with new solder smoothly when the sample is taken out of the solder bath.	
Resistance to Soldering heat (reflow soldering)	There shall be no damage or problems.	Temperature profile of reflow soldering  soldering (Peak temperature 260±5°C 10 sec)  Pre-heating  150  200  150  2 min  Slow cooling (Stored at room temperature)  2 min  2 min. or more  Solder temperature: 260 ±5°C  Dip time: 10 ±1 seconds  The chip shall not crack.  More than 75% of the terminal electrode shall be covered with solder.	



### **ENVIROMENT CHARACTERISTICS**

TEST ITEM	SPECIFICATION	
High temperature	∆L/Lo≦±5%	1000hrs.at rated operating temperature (e.g. 155°C part
storage		can be stored for 1000hrs.@ 155°C.Same applies for 125°C
	There shall be	and 105°C. Unpowered. Measurement at 24±4 hours after test
	no mechanical	conclusion.
	damage.	
Temperature	∆L/Lo≦±5%	1000cycles (-40°C to +155°C).Note: If 105°C part or 125°C
Cycling		part the 1000cycles will be at that temperature.
	There shall be	Measurement at 24±4hours after test conclusion. 30min
	no other dama-	maximum dwell time at each temperature extreme.1min.
	ge of problems	maximum transition time.
Operational Life	∆L/Lo≦±5%	1000hrs. @155°C. If 105°C or 125°C part will be Tested at that temperature. Measurement at 24±4 hours after test
	There shall be	conclusion
	no mechanical	
	damage.	
Biased Humidity	∆L/Lo≦±5%	1000hours 85°C/85%RH. Unpowered.Measurement
		at 24±4hours after test conclusion.
	There shall be	
	no mechanical	
	damage.	

#### Test conditions:

The sample shall be reflow soldered onto the printed circuit board in every test.

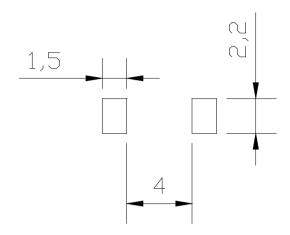


## (5) LAND DIMENSION (Ref.)

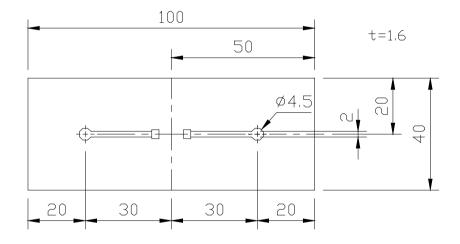
PCB: GLASS EPOXY t=1.6mm

## (5)-1 LAND PATTERN DIMENSIONS

(STANDARD PATTERN) Unit: mm



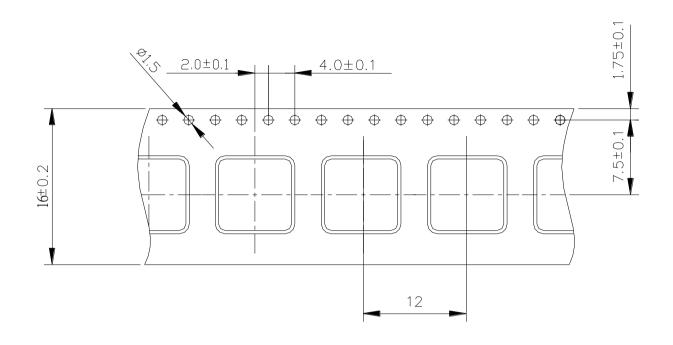
### (5)-2 SUBSTRATE BENDING TEST BENDING TEST BOARD



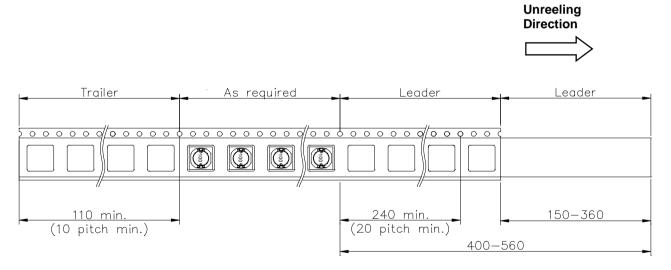


## (6) PACKAGING

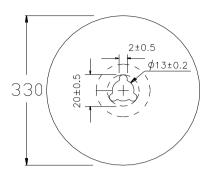
## (6)-1 CARRIER TAPE DIMENSIONS (mm)

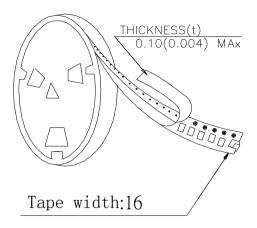


## (6)-2 TAPING DIMENSIONS (mm)



## (6)-3 REEL DIMENSIONS (mm)





## (6)-4 QUANTITY

1000 pcs /Reel

The products are packaged so that no damage will be sustained.

Please note that the contents may change without any prior notice due to reasons such as upgrading.

